Abstract

APPARATUS FOR DELIVERING SEMICONDUCTOR COMPONENTS TO A SUBSTRATE DURING SEMICONDUCTOR PACKAGE MANUFACTURING

An apparatus 200 for delivering semiconductor components 212 to a substrate 206a; 206b; 500a; 500b; 500c during semiconductor package manufacturing is disclosed. The apparatus 200 comprises a platform 216 and a plurality of delivery modules 202a, 202b affixed to the platform 216. Each of the plurality of delivery modules 202a, 202b has a support device 204a; 204b for supporting the substrate 206a; 206b; 500a; 500b; 500c, as well as a delivery device 208a; 208b for delivering the semiconductor components 212 to the substrate 206a; 206b; 500a; 500b; 500c. In particular, heights of the support devices 204a, 204 are mutually levelled for conveying the substrate 206a; 206b; 500a; 500b; 500c between the plurality of delivery modules 202a, 202b.

[FIG. 2]